

Products/Modules

	Products	Modules	Mesh Technology		
			eDesign	Shell	Solid
Thermoplastic	eDesign Basic	Flow	●		
	eDesign	Flow, Pack, Cool, Warp, MCM	●		
	Professional	Flow, Pack, Cool, Warp, MCM	●	●	
	Advanced	Flow, Pack, Cool, Warp, MCM	●	●	●
	Solution Add-on	Fiber	●	●	●
		Advanced Hot Runner	●		●
		Injection Compression		●	
		Co-Injection		●	
		Gas-Assisted Injection	●	●	
		Water-Assisted Injection		●	
		MuCell®		●	
		Viscoelasticity	●		●
		Optics		●	
		Expert	●	●	●
		Stress	●		●
		FEA Interface	●	●	●
		Digimat Interface	●		●
Thermoset (RIM)	eDesign Basic	Flow	●		
	eDesign	Flow, Pack, Cool, Warp, MCM	●		
	Professional	Flow, Pack, Cool, Warp, MCM	●	●	
	Advanced	Flow, Pack, Cool, Warp, MCM	●	●	●
	Solution Add-on	Fiber	●	●	●
		Stress	●		●
		FEA Interface	●	●	●
		Encapsulation		●	
		Underfill		●	
Solution Manager	Post-Processing	Project	●	●	●

Moldex3D FEA Interface include interface modules to Abaqus, ANSYS, MSC.Nastran, Nastran, NENAstran, NXNastran, LS-DYNA, Marc, Radioss.

System Requirements :

1. Microsoft Windows 7, Windows Vista, Windows Server 2008, Windows HPC Server 2008.
2. Intel Core i7, Intel Core2Duo, Intel Pentium, Intel Xeon, Intel EM64T, AMD Athlon or AMD Opteron Based Processor.
3. 8 GB RAM or greater.

MuCell® is a registered trademark of Trexel, Inc.